



ADMER™ RA206E

PP-Grade
MFR: 28
Density: 0.90

Technical Data Sheet

Preface

ADMER™ RA206E is a maleic anhydride grafted PP-based compatibilizer. Used in post-industrial recycling application, it offers physical bonding to PP phase and chemical bonding to polar phases (PA or EVOH). As a result, **ADMER™ RA206E** provides homogenized polymer blends with a fine phase morphology and improved mechanical and optical properties.

Properties

Item	Value	Unit	ASTM Testing Method
MFR (230°C, 2.16kg)	28	g/10 min	D1238
Density	0.90	g/cm ³	D1505
Melting Point	141	°C	D3418



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Processing

The recommended processing temperatures for ADMER™ can be found in our temperature proposal.

Maximum temperature: 300 °C; Temperatures above the upper limit or long residence times of molten resin may lead to decomposition of the polymer. Decomposition products may be carbon monoxide, carbon dioxide, hydrocarbons and water.

Whilst the extrusion process is either interrupted or terminated:

Less than 2 hours: Screw rotation can be stopped maintaining temperature.

More than 2 hours: Purge out and shut down in accordance with common procedure.

Handling

ADMER™ resins are supplied in the form of small, free flowing pellets and can be easily handled with commercially available equipment. We recommend to store ADMER™ at a dry and clean place at room temperature without sunlight exposure. Precaution should be taken in opening the package to avoid contamination by foreign materials.

Since ADMER™ is a non-hygroscopic material, it absorbs less moisture than non-polyolefin polymers. Therefore, ADMER™ does not require drying prior to processing.

ADMER™ can be re-used, recycled or incinerated with energy recovery. We do not recommend disposing of ADMER™ on a landfill. However, any disposal must comply with local regulations and recommendations.

Disclaimer:

The information and numerical results are for information only and are given in good faith.

In view of numerous factors of which we are unaware and which are beyond our control regarding the use of our products, we cannot guarantee that this information covers all possible aspects of the subject. Moreover, we cannot accept any responsibility with regard to patents for applications and processes described.